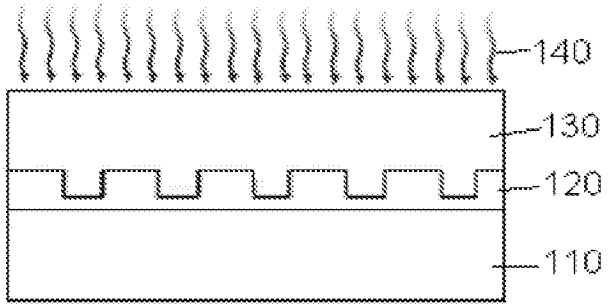


Fig. 1a

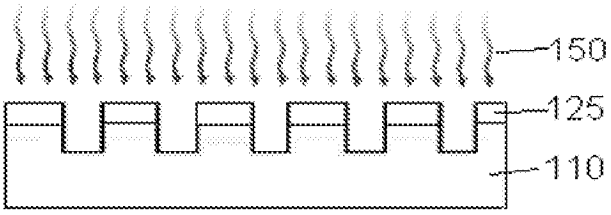


Fig. 1b

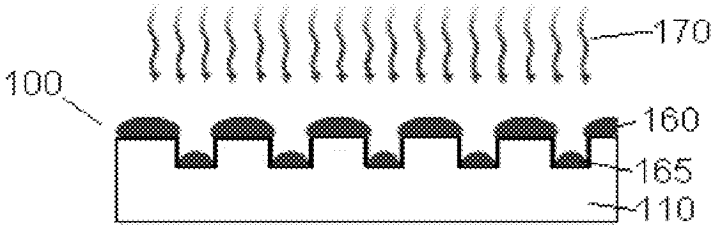


Fig. 1c

Fig. 1

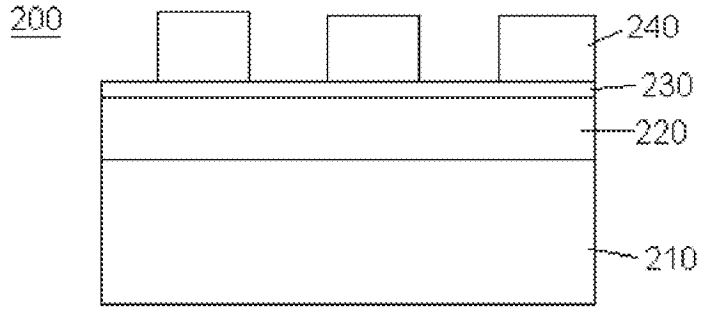


Fig. 2a

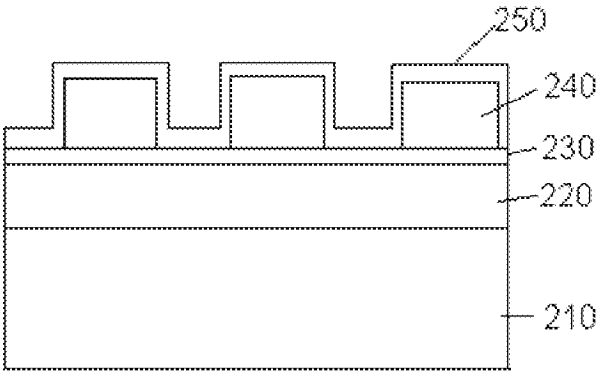


Fig 2b

Fig. 2

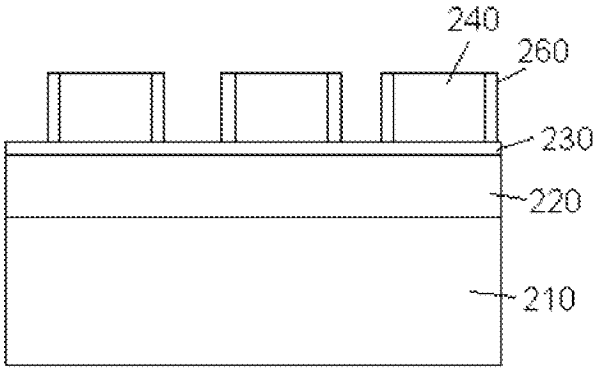


Fig. 2c

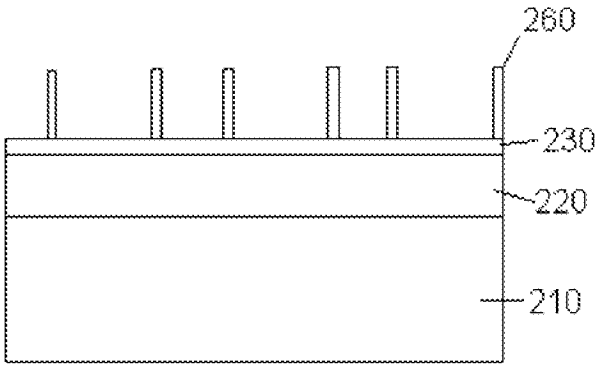


Fig. 2d

Fig. 2

205

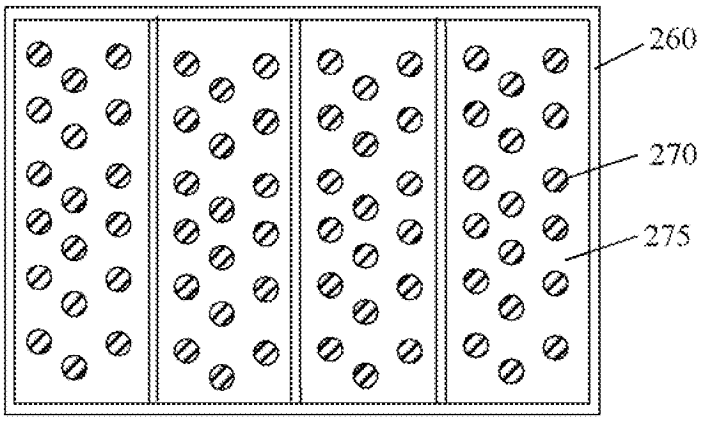


Fig. 3

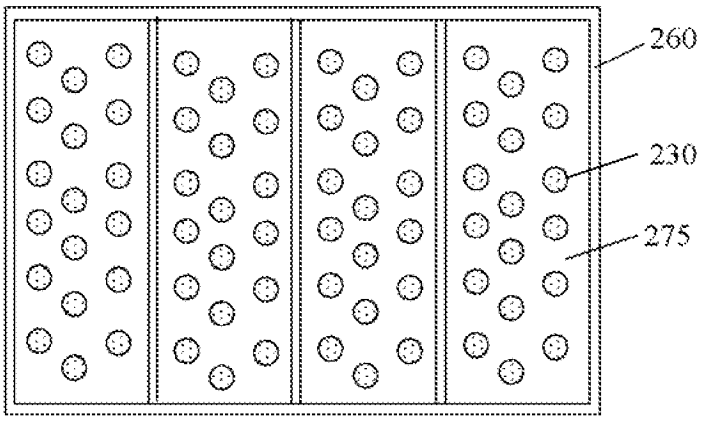


Fig. 4

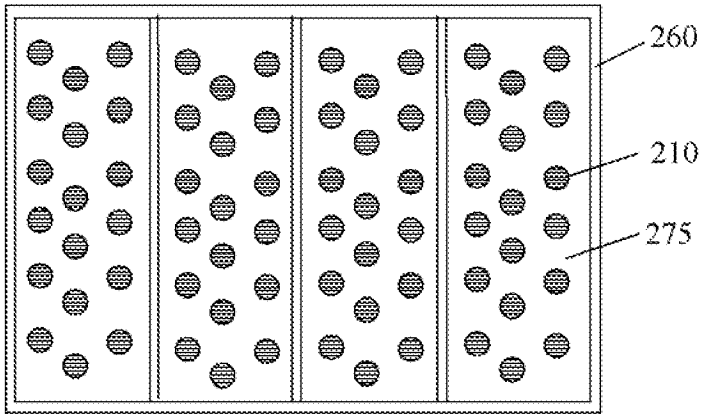


Fig. 5

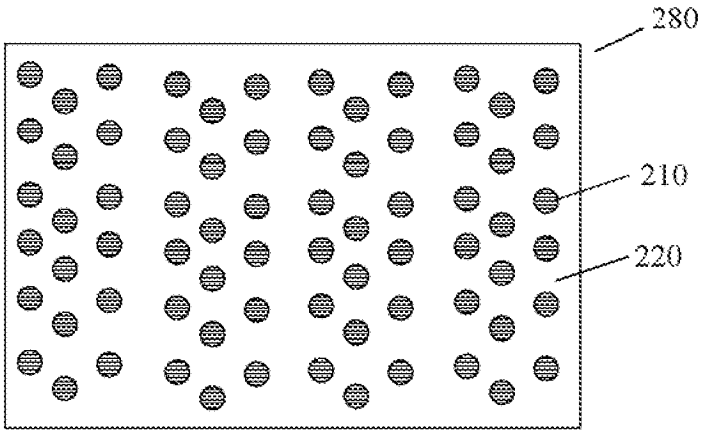


Fig. 6

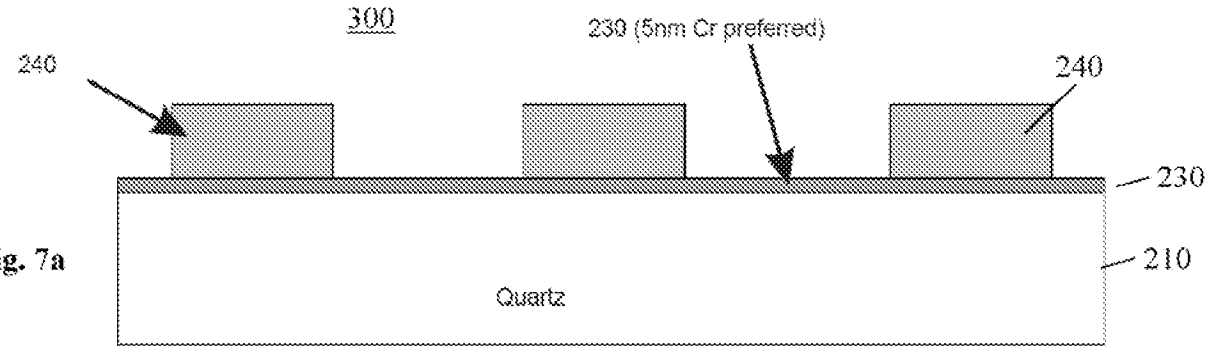


Fig. 7a

1) Starting substrate and layers (use same numbering as disclosure)

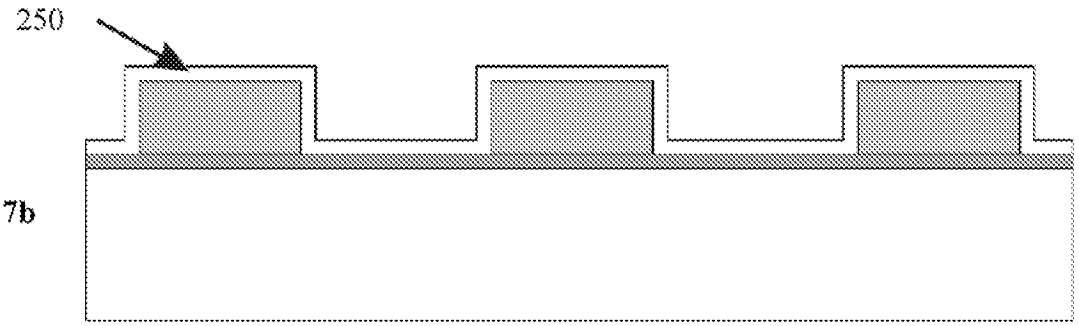


Fig. 7b

2) Conformal coating as described in disclosure

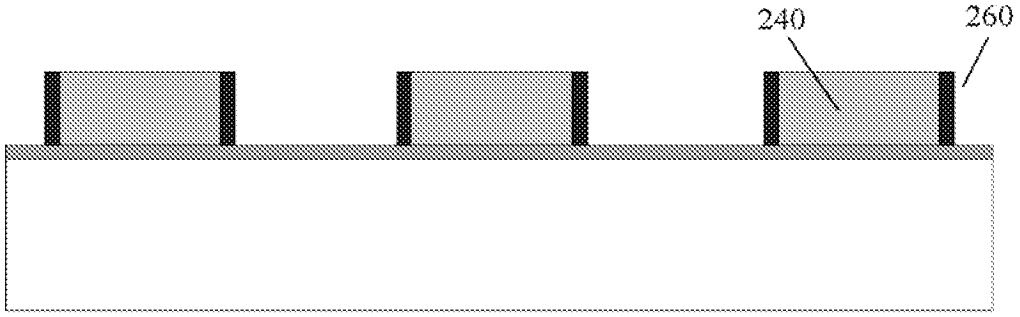


Fig. 7c

3) Thin wall formation

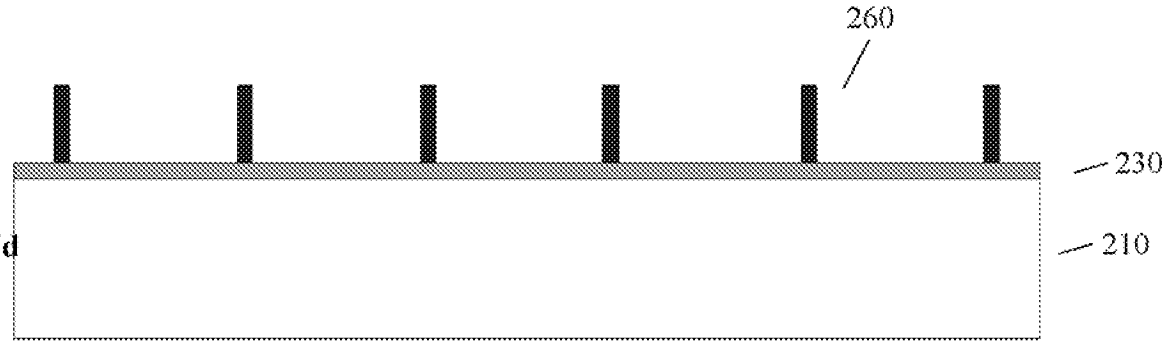


Fig. 7d

4) Thin wall formation (continued)

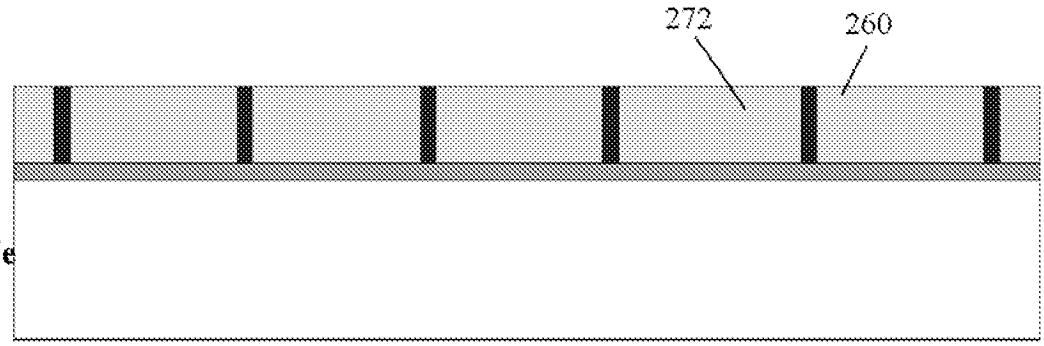


Fig. 7e

5) DBCP coating

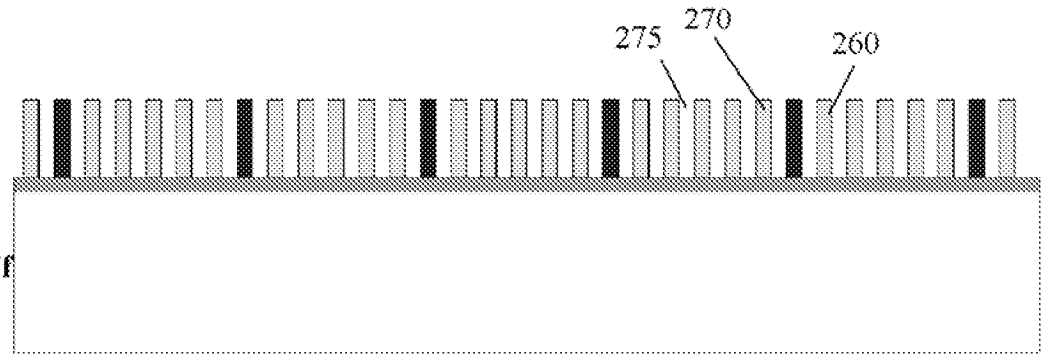


Fig. 7f

6) DBCP microphase separation to form cylindrical pillars

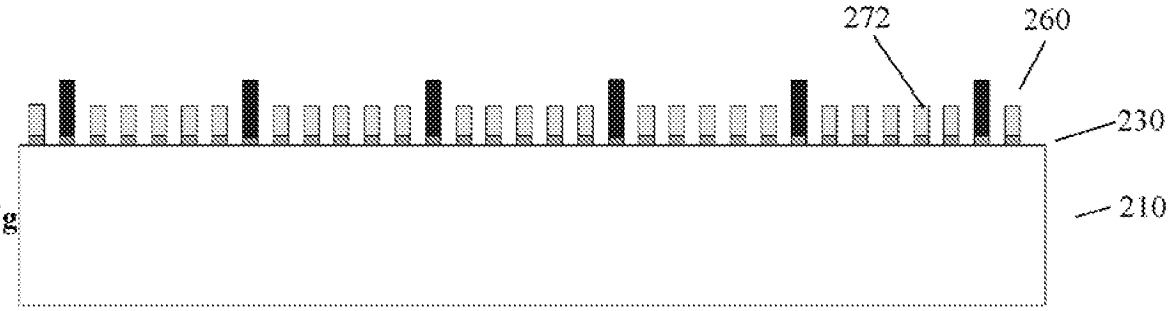


Fig. 7g

7) Transfer pattern into Cr layer by reactive-ion etching

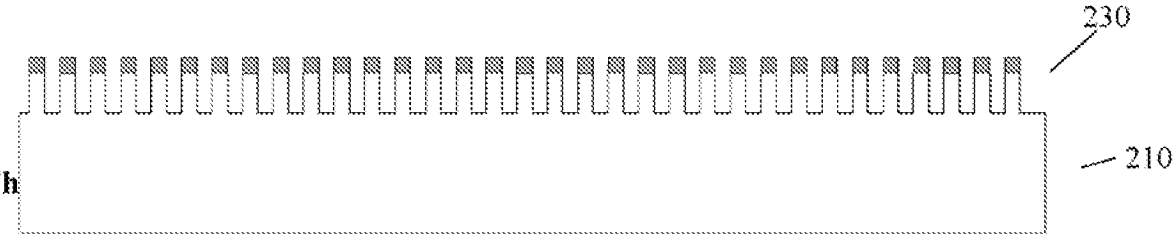


Fig. 7h

8) Transfer pattern into quartz by RIE (e.g. using CF4 plasma)

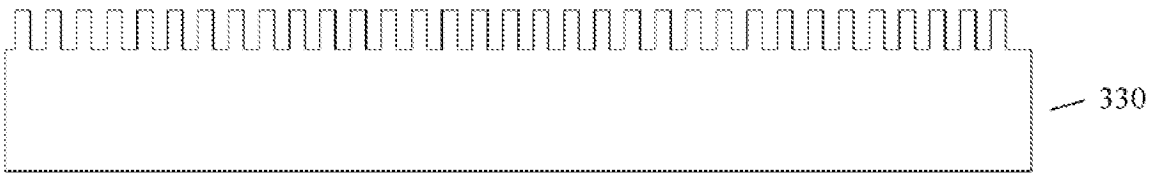


Fig. 7i

9) Remove Cr mask by wet etching